



**EVERLIGHT ELECTRONICS CO.,LTD.**

# DATA SHEET

**PART NO. : 17-215/G6C-FN2P2B/3T**

**DATE :**

**DEPARTMENT : R.D.3**

**REVISION : 1.3**

<b>RECEIVED</b>			
MASS PRODUCTION			
PRELIMINARY			
CUSTOMER DESIGN			
DEVICE NUMBER : DSE-175-G01			
PAGE : 13			
CUSTOMER	DESIGNER	CHECKER	APPROVER
	JESSICA CHANG	JEFF TSAI	CHARLES CHANG

REV	DESCRIPTION	RELEASE DATE

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TEL : 886-2-2267-2000,2266-9936 ( 22 Lines )

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<http://www.everlight.com>

**Package Type:**

SMD For PCB Type

11-21	19-215
12-21	19-215A
12-215	19-217A
15-21	22-21
15-215	23-21
16-213	23-21B
17-21	24-21
17-215	25-21
19-21	27-21
19-21A	42-21

**Dominant Wavelength Groups:**  
According to the difference wavelength to define

None: No definition

A : Standard wavelength definition.

B : Range of wavelength definition is more narrowly than group A.

C : Range of wavelength definition is more narrowly than group A, but the value is different with group B.

F : The wavelength definition in special specification.

The dominant wavelength data did not including ±1nm testing tolerance.

**Test Forward Current:**

None: 20 mA  
Y : 5 mA  
Z : 10 mA

**Taping Quantity:**

1: 1000 pcs (Taping)  
2: 2000 pcs (Taping)  
3: 3000 pcs (Taping)  
5: 5000 pcs (Taping)  
C : 1500 pcs (Taping)  
D : 10000 pcs (Taping)

**Packing Method :**

A: Reverse-side placement  
B: Reverse-side placement (Anode toward the sprocket hole)  
C: Right-side placement  
D: Right-side placement (Anode toward the sprocket hole)  
T: Top-side placement  
R: Top-side placement (Anode toward the sprocket hole)

**19 - 21 / B H C - A N1 P2 M / 3 T**

**Emission Color:**

R: Red  
(λ d: 640nm, 630nm, 625nm)

S: Sunset Orange  
(λ d: 615nm, 605nm)

Y: Yellow  
(λ d: 595nm, 590nm)

G: Green  
(λ d: 570nm, 565nm, 560nm, 525nm, 505nm)

B: Blue  
(λ d: 470nm)

W: White x=0.32 y=0.31

The ordinal number that base on diffence electro-optical characteristics within chip.

1,2 ..... 7,8,9,  
A,B.....X,Y,Z

**Resin Color:**

C: Water Clear  
W: White Diffused  
D: Diffused

**Luminous Intensity Groups:**

C0: 0.28 ... 0.45	R ⇨ R1: 112 ... 140
D0: 0.45 ... 0.70	R2: 140 ... 180
E0: 0.70 ... 1.1	S1: 180 ... 225
F0: 1.1 ... 1.8	S2: 225 ... 285
G0: 1.8 ... 2.8	T1: 285 ... 360
H0: 2.8 ... 4.5	T2: 360 ... 450
J0: 4.5 ... 7.2	U1: 450 ... 565
K0: 7.2 ... 11.5	U2: 565 ... 715
L1: 11.5 ... 14.5	V1: 715 ... 900
L2: 14.5 ... 18.0	V2: 900 ... 1120
M1: 18.0 ... 22.5	W1: 1120 ... 1420
M2: 22.5 ... 28.5	W2: 1420 ... 1800
N1: 28.5 ... 36.0	X1: 1800 ... 2250
N2: 36.0 ... 45.0	X2: 2250 ... 2850
P1: 45.0 ... 57.0	Y1: 2850 ... 3600
P2: 57.0 ... 72.0	Y2: 3600 ... 4500
Q1: 72.0 ... 90.0	
Q2: 90.0 ... 112	

Unit: mcd

The luminous intensity data did not including ±15% testing tolerance.

**Forward Voltage Groups:**  
None: No definition

The VF definition as follows:

Forward Voltage Group	Bin	Min.	Max.
A	0	1.55	1.75
	1	1.75	1.95
	2	1.95	2.15
	3	2.15	2.35
B	4	2.35	2.55
	5	2.55	2.75
	6	2.75	3.05
	7	3.05	3.35
C	8	3.35	3.65
	9	2.50	2.70
	10	2.70	2.90
	11	2.90	3.10
D	12	3.10	3.30
	13	3.30	3.50
	14	3.50	3.70
	15	2.70	2.85
E	16	2.85	3.00
	17	3.00	3.15
	18	3.15	3.30
	F		
G			
H			
I			
J			
K			
L			
M			
N			
O			
P			
Q			
R			
S			
T			

The forward voltage data did not including ±0.1V testing tolerance.

# ANNEX



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■ Dominant Wavelength Groups:

Chip	G2	Range			
Dom . Wavelength	Of Group	Bin	Min.	Max.	Unit
A	A	C10	557.5	559.5	nm
		C11	559.5	561.5	nm
		C12	561.5	563.5	nm
		C13	563.5	565.5	nm
		C14	565.5	567.5	nm

Chip	GV	Range			
Dom . Wavelength	Of Group	Bin	Min.	Max.	Unit
A	A	C13	563.5	565.5	nm
		C14	565.5	567.5	nm
		C15	567.5	569.5	nm
		C16	569.5	571.5	nm

Chip	G3	Range			
Dom . Wavelength	Of Group	Bin	Min.	Max.	Unit
A	B	C11	559.5	561.5	nm
		C12	561.5	563.5	nm
		C13	563.5	565.5	nm
		C14	565.5	567.5	nm
			C15	567.5	569.5

Chip	GP	Range			
Dom . Wavelength	Of Group	Bin	Min.	Max.	Unit
A	A	C10	557.5	559.5	nm
		C11	559.5	561.5	nm
		C12	561.5	563.5	nm
		C13	563.5	565.5	nm
		C14	565.5	567.5	nm

Chip	G5	Range			
Dom . Wavelength	Of Groups	Bin	Min.	Max.	Unit
A	B	C15	567.5	569.5	nm
		C16	569.5	571.5	nm
		C17	571.5	573.5	nm
			C18	573.5	575.5

Chip	G6,G7	Range			
Dom . Wavelength	Of Group	Bin	Min.	Max.	Unit
A	B	C15	567.5	569.5	nm
		C16	569.5	571.5	nm
		C17	571.5	573.5	nm
		C18	573.5	575.5	nm
			C19	575.5	577.5
F	F	CC2	570.0	571.5	nm
		CC3	571.5	573.0	nm
		CC4	573.0	574.5	nm

# ANNEX



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■ Dominant Wavelength Groups:

Chip	GH		Range			
Dom . Wavelength			Range			
Of Group			Bin	Min.	Max.	Unit
A	C	B10	517.5	519.5	nm	
			B11	519.5	521.5	nm
			B12	521.5	523.5	nm
	B	C	B13	523.5	525.5	nm
			B14	525.5	527.5	nm
			B15	527.5	529.5	nm
			B16	529.5	531.5	nm
			B17	531.5	533.5	nm
			B18	533.5	535.5	nm
Z	F	G	BB1	519.5	521.0	nm
			BB2	521.0	522.5	nm
			BB3	522.5	524.0	nm
			BB4	524.0	525.5	nm
			BB5	525.5	527.0	nm
			BB6	527.0	528.5	nm
			BB7	528.5	530.0	nm
			BB8	530.0	531.5	nm
			BB9	531.5	533.0	nm
Z	X	Y	W	515	520	nm
			X	520	525	nm
			Y	525	530	nm
			Z	530	535	nm

Chip	GL		Range			
Dom . Wavelength			Range			
Of Group			Bin	Min.	Max.	Unit
A	A	A	B1	499.5	501.5	nm
			B2	501.5	503.5	nm
			B3	503.5	505.5	nm
			B4	505.5	507.5	nm
			B5	507.5	509.5	nm
			B6	509.5	511.5	nm
			B7	511.5	513.5	nm
			B8	513.5	515.5	nm
Z	X	Y	W	495	500	nm
			X	500	505	nm
			Y	505	510	nm
			Z	510	515	nm

# ANNEX



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■ Forward Voltage Groups:

Forward Voltage Groups				Range				
				Bin	Min.	Max.	Unit	
				A	00	1.55	1.75	v
					0	1.75	1.95	v
C B				A	1	1.95	2.15	v
					2	2.15	2.35	v
C B				A	3	2.35	2.55	v
					4	2.55	2.75	v
M E D				D	5	2.75	3.05	v
					6	3.05	3.35	v
M E D				D	7	3.35	3.65	v
					8	3.65	3.95	v
N F K R J				J	9	2.50	2.70	v
					10	2.70	2.90	v
N F K R J				J	11	2.90	3.10	v
					12	3.10	3.30	v
N F K R J				J	13	3.30	3.50	v
					14	3.50	3.70	v
P H				H	15	2.70	2.85	v
					16	2.85	3.00	v
					17	3.00	3.15	v
					18	3.15	3.30	v



**Technical Data Sheet**

**0.8mm Height Flat Top LED**

17-215/G\_\_C Series \*1

**Features**

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.



**Descriptions**

- The 17-215 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

**Applications**

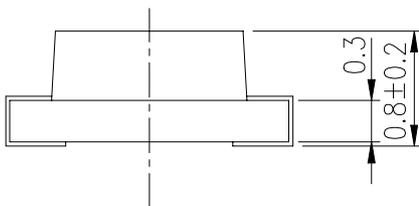
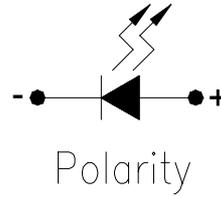
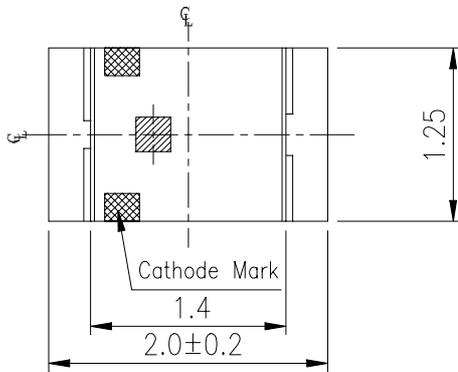
- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

**Device Selection Guide**

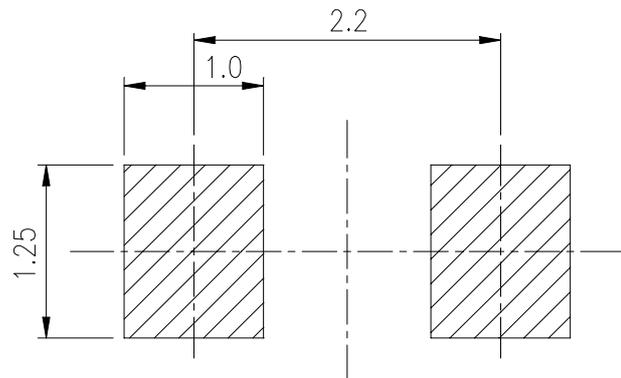
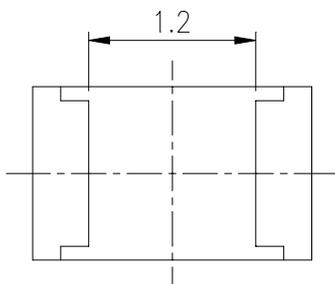
Part No.	Chip		Lens Color
	Material	Emitted Color	
17-215/G2C	GaP	Pure Green	Water Clear
17-215/G3C		Pale Green	
17-215/G5C		Yellow Green	
17-215/G6C	AlGaInP	Brilliant Yellow Green	
17-215/GLC	InGaN	Bluish Green	
17-215/GHC	InGaN	Brilliant Green	
17-215/GPC	AlGaInP	Pale Green	

\*1. The series is included 17-215/G2C,17-215/G3C,17-215/G5C, 17-215/G6C,17-215/GLC,17-215/GHC,and 17-215/GPC.

Package Outline Dimensions



For reflow soldering (propose)



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  , Angle  $\pm 0.5^\circ$  ,Unit = mm

**Absolute Maximum Ratings (Ta=25°C)**

Series	Parameter	Symbol	Rating	Unit
17-215/G_C Series	Reverse Voltage	V <sub>R</sub>	5	V
17-215/G_C Series	Forward Current	I <sub>F</sub>	30	mA
17-215/ G6C/GLC/GHC/GPC			25	
17-215/G_C Series	Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
17-215/G_C Series	Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
17-215/G_C Series	Soldering Temperature	T <sub>sol</sub>	260 (for 5 seconds)	°C
17-215/G_C Series	Electrostatic Discharge	ESD	2000	V
17-215/GLC/GHC			150	
17-215/G_C Series	Power Dissipation	P <sub>d</sub>	130	mW
17-215/G2C/G3C/G5C			100	
17-215/G6C/GPC			60	
17-215/G_C Series	Peak Forward Current (Duty 1/10 @1KHz)	I <sub>F</sub>	60	mA
17-215/GLC/GHC			100	

**Electro-Optical Characteristics (Ta=25°C)**

Part No.	Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
17-215/G2C	Peak Wavelength	$\lambda_p$	----	555	----	nm	IF=20mA
17-215/G3C				560			
17-215/G5C				570			
17-215/G6C				575			
17-215/GLC				502			
17-215/GHC				518			
17-215/GPC				561			
17-215/G2C				Dominant Wavelength			
17-215/G3C	565						
17-215/G5C	571						
17-215/G6C	573						
17-215/GLC	505						
17-215/GHC	525						
17-215/GPC	562						

**Electro-Optical Characteristics (Ta=25°C)**

Part No.	Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
17-215/G2C	Spectrum Radiation Bandwidth	$\Delta \lambda$	----	30	----	nm	IF=20mA
17-215/G3C				30			
17-215/G5C				30			
17-215/G6C				20			
17-215/GLC				30			
17-215/GHC				36			
17-215/GPC				20			
17-215/G_C Series	Viewing Angle	$2\theta_{1/2}$	----	130	----	deg	
17-215/G_C Series	Forward Voltage	V <sub>F</sub>	----	2.0	2.4	V	
17-215/GLC/GHC				3.5	4.0		
17-215/G_C Series	Reverse Current	I <sub>R</sub>	----	----	10	$\mu A$	V <sub>R</sub> =5V
17-215/GLC/GHC					50		

**Note:**

- 1. Tolerance of Forward Voltage  $\pm 0.1V$**

**17-215/G\_\_C Series Explain Of Luminous Intensity:**
**I<sub>F</sub>=20mA**

Part No.	Parameter	Symbol	Typ.	Bin Code	Min.	Max.	Unit
17-215/G2C-G0J0	Luminous Intensity	I <sub>v</sub>	3.0	G0	1.8	2.8	mcd
				H0	2.8	4.5	
				J0	4.5	7.2	
17-215/G3C-J0L1	Luminous Intensity	I <sub>v</sub>	7.5	J0	4.5	7.2	mcd
				K0	7.2	11.5	
				L1	11.5	14.5	
17-215/G5C-K0L2	Luminous Intensity	I <sub>v</sub>	12	K0	7.2	11.5	mcd
				L1	11.5	14.5	
				L2	14.5	18.0	

**Note:**

 The luminous intensity data did not including  $\pm 15\%$  testing tolerance.

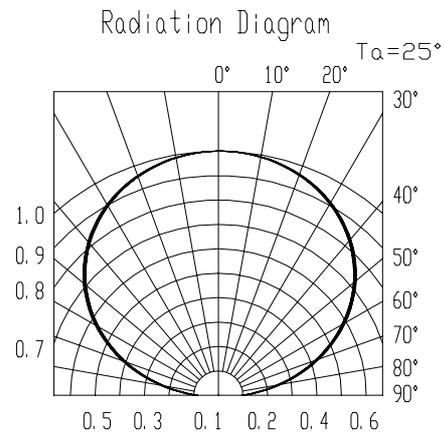
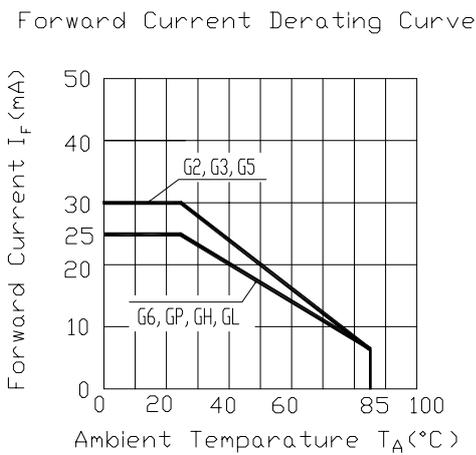
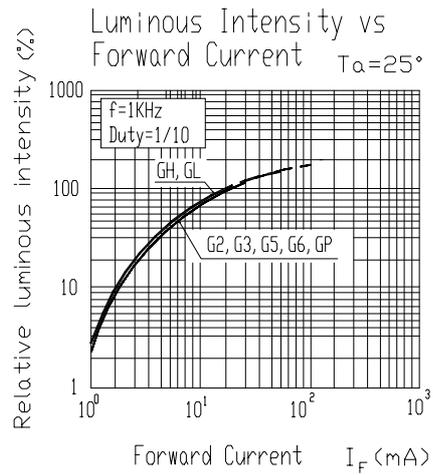
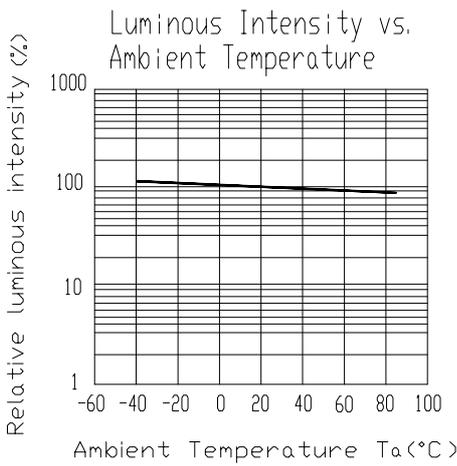
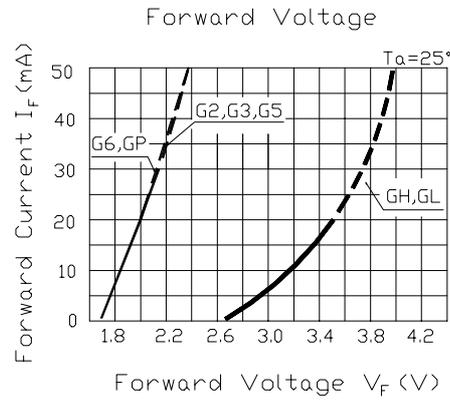
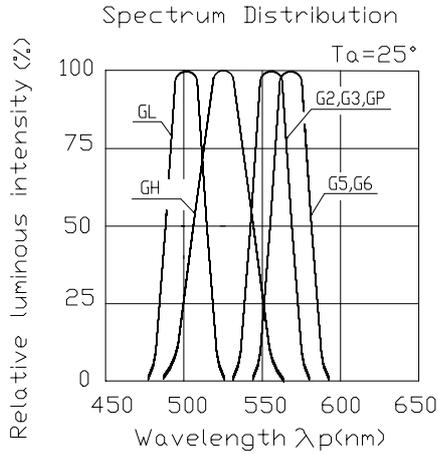
**17-215/G\_\_C Series Explain Of Luminous Intensity:**
**I<sub>F</sub>=20mA**

Part No.	Parameter	Symbol	Typ.	Bin Code	Min.	Max.	Unit
17-215/G6C-L2M2	Luminous Intensity	I <sub>v</sub>	25	L2	14.5	18.0	mcd
				M1	18.0	22.5	
				M2	22.5	28.5	
17-215/G6C-MN	Luminous Intensity	I <sub>v</sub>	35	M	18.0	28.5	mcd
				N	28.5	45.0	
17-215/G6C-N1P1	Luminous Intensity	I <sub>v</sub>	45	N1	28.5	36.0	mcd
				N2	36.0	45.0	
				P1	45.0	57.0	
17-215/G6C-N2P2	Luminous Intensity	I <sub>v</sub>	55	N2	36.0	45.0	mcd
				P1	45.0	57.0	
				P2	57.0	72.0	
17-215/GLC-Q1R2	Luminous Intensity	I <sub>v</sub>	120	Q1	72.0	90.0	mcd
				Q2	90.0	112	
				R1	112	140	
				R2	140	180	
17-215/GHC-R1S2	Luminous Intensity	I <sub>v</sub>	170	R1	112	140	mcd
				R2	140	180	
				S1	180	225	
				S2	225	285	
17-215/GPC-K0M1	Luminous Intensity	I <sub>v</sub>	15	K0	7.2	11.5	mcd
				L1	11.5	14.5	
				L2	14.5	18.0	
				M1	18.0	22.5	

**Note:**

 The luminous intensity data did not including  $\pm 15\%$  testing tolerance.

Typical Electro-Optical Characteristics Curves

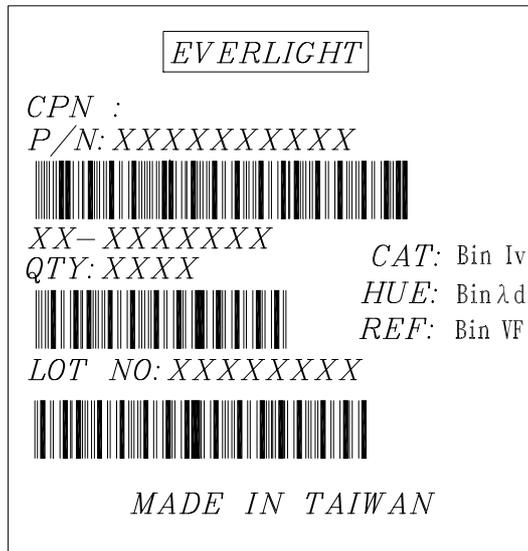


**Label explanation**

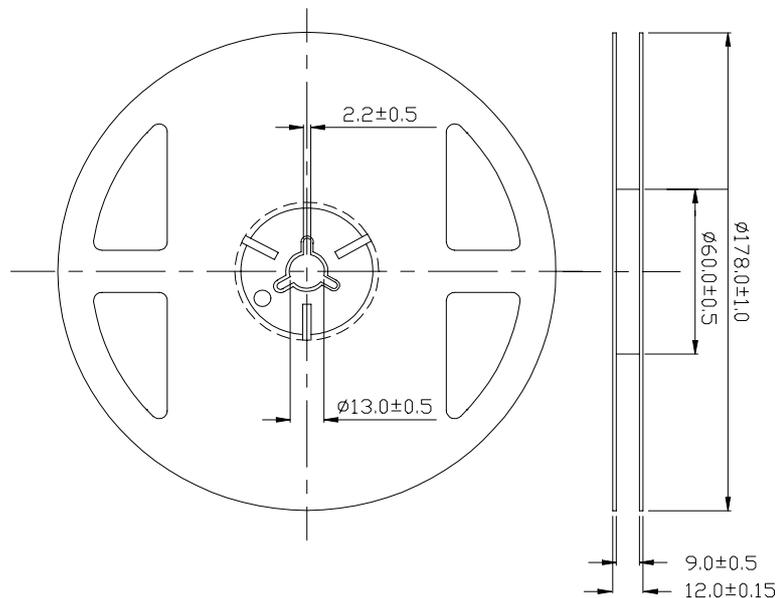
**CAT: Luminous Intensity Rank**

**HUE: Dom. Wavelength Rank**

**REF: Forward Voltage Rank**



**Reel Dimensions**



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  ,Unit = mm



**Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 240°C ± 5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -55°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	IF = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 Hrs.	22 PCS.	0/1

## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

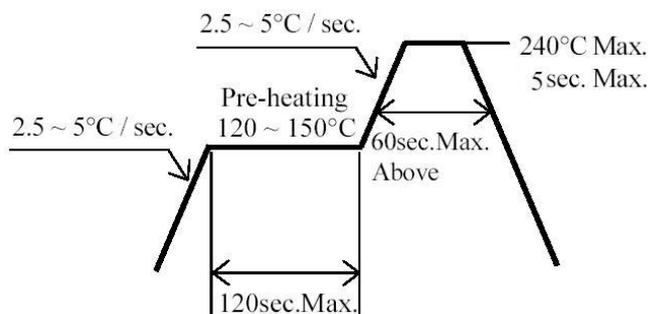
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60± 5°C for 24 hours.

### 3. Soldering Condition

#### 3.1 Lead solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

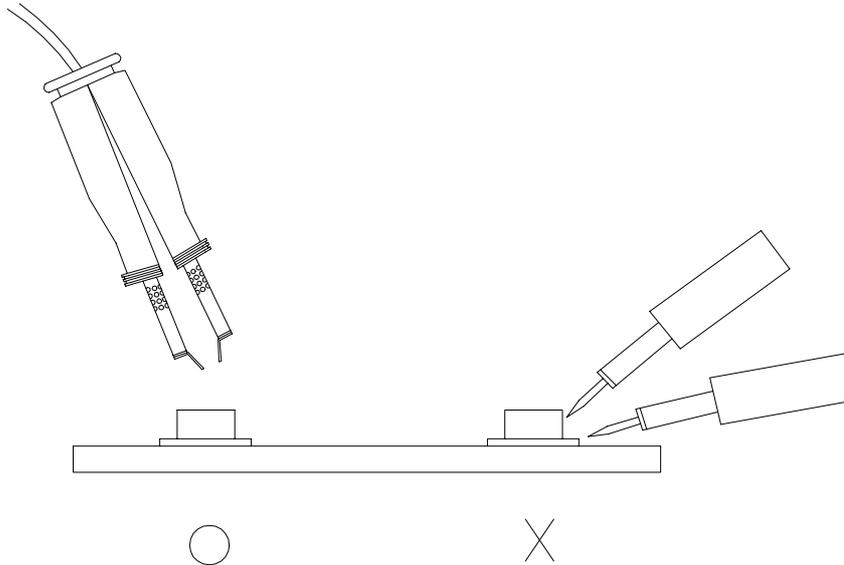
3.4 After soldering, do not warp the circuit board.

### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 280°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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[>>Everlight \(亿光\)](#)